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TI Silver alloy for brazes
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SO Jpn. Tokkyo Koho, 3 pp.
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PI	JP 62036798	B4	19870808	JP 1979-81796	19790628 <--
AB	The brazes contg. 63-90% Ag, 0.05-4.5% Ni, Sn, and/or In, and balance Cu are used in vacuum tubes, electronic tubes, or large-scale integrated circuits to develop smooth joints for low corrosion and discoloring. Thus, a Cu specimen was brazed with Ag alloy contg. Cu 36, In 0.1, and Sn 0.15%. Surface crack no. was 3, and av. depth of cracks on the brazed surface was 2.mu., vs. 12 and 6.5.mu. when Ag-34% Cu braze was used.				